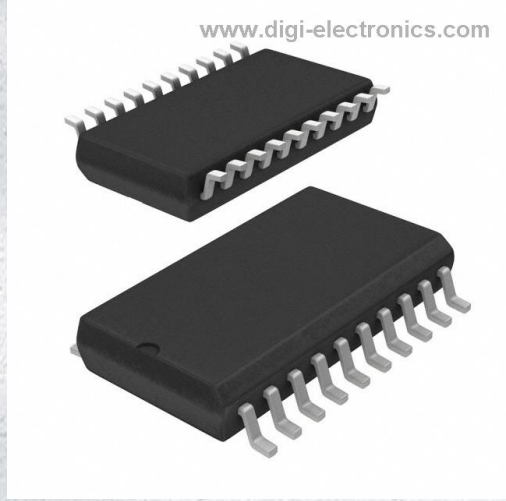
MC100LVEL39DWR2G Datasheet



DiGi Electronics Part Number	MC100LVEL39DWR2G-DG
Manufacturer	onsemi
Manufacturer Product Number	MC100LVEL39DWR2G
Description	IC CLOCK GENERATOR 20SOIC
Detailed Description	Clock Generator IC 1GHz 1 20-SOIC (0.295", 7.50mm Width)

https://www.DiGi-Electronics.com

Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
MC100LVEL39DWR2G	onsemi
Series:	Product Status:
100LVEL	Active
DiGi-Electronics Programmable:	Type:
Not Verified	Clock Generator
PLL:	Input:
No	LVDS, NECL, PECL
Output:	Number of Circuits:
ECL	1
Ratio - Input:Output:	Differential - Input:Output:
1:4	Yes/Yes
Frequency - Max:	Divider/Multiplier:
1GHz	Yes/No
Voltage - Supply:	Operating Temperature:
3V ~ 3.8V	-40°C ~ 85°C
Mounting Type:	Package / Case:
Surface Mount	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package:	Base Product Number:
20-SOIC	MC100

Environmental & Export classification

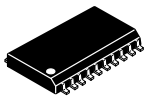
RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	3 (168 Hours)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8542.39.0001	

onsemi

DATA SHEET
www.onsemi.com

3.3 V ECL ÷2/4, ÷4/6 Clock Generation Chip

MC100LVEL39



SOIC−20 WB
DW SUFFIX
CASE 751D

Description

The MC100LVEL39 is a low skew ÷2/4, ÷4/6 clock generation chip designed explicitly for low skew clock generation applications. The internal dividers are synchronous to each other, therefore, the common output edges are all precisely aligned. The device can be driven by either a differential or single-ended input signal. In addition, by using the V_{BB} output, a sinusoidal source can be AC coupled into the device.

The common enable ($\overline{EN}$) is synchronous so that the internal dividers will only be enabled/disabled when the internal clock is already in the LOW state. This avoids any chance of generating a runt clock pulse on the internal clock when the device is enabled/disabled as can happen with an asynchronous control. An internal runt pulse could lead to losing synchronization between the internal divider stages. The internal enable flip-flop is clocked on the falling edge of the input clock, therefore, all associated specification limits are referenced to the negative edge of the clock input.

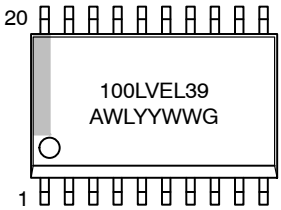
Upon startup, the internal flip-flops will attain a random state; therefore, for systems which utilize multiple LVEL39s, the Master Reset (MR) input must be asserted to ensure synchronization. For systems which only use one LVEL39, the MR pin need not be exercised as the internal divider design ensures synchronization between the ÷2/4 and the ÷4/6 outputs of a single device.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- 50 ps Maximum Output-to-Output Skew
- Synchronous Enable/Disable
- Master Reset for Synchronization
- ESD Protection: Human Body Model; > 2 kV
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range:
  V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range:
  V_{CC} = 0 V with V_{EE} = −3.0 V to −3.8 V
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)
  - For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−0 @ 0.125 in,
  Oxygen Index: 28 to 34

MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

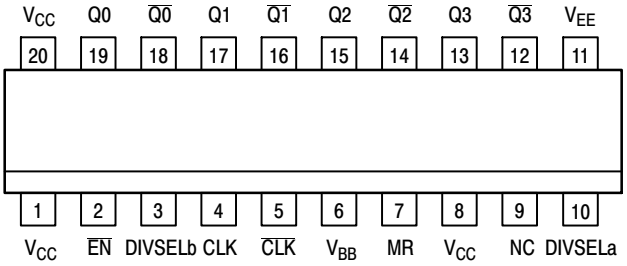
ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL39DWR2G	SOIC−20 WB (Pb-Free)	1000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

- Transistor Count = 419 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MC100LVEL39



Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Pinout: SOIC−20 WB (Top View)

Table 1. PIN DESCRIPTION

Column Head	
CLK, $\overline{CLK}$	ECL Diff Clock Inputs
Q_0, Q_1; $\overline{Q_0}$, $\overline{Q_1}$	ECL Diff ÷2/4 Outputs
Q_2, Q_3; $\overline{Q_2}$, $\overline{Q_3}$	ECL Diff ÷4/6 Outputs
DIVSELa, DIVSELb	ECL Frequency Select Inputs
$\overline{EN}$	ECL Sync Enable
MR	ECL Master Reset
V_{BB}	Reference Voltage Output
V_{CC}	Positive Supply
V_{EE}	Negative Supply
NC	No Connect

Table 2. FUNCTION TABLE

CLK	$\overline{EN}$	MR	Function
Z	L	L	Divide
ZZ	H	L	Hold Q0−3
X	X	H	Reset Qo−3

Z = Low-to-High Transition
ZZ = High-to-Low Transition
X = Don't Care

DIVSELa	Q_0, Q_1 Outputs
L	Divide by 2
H	Divide by 4
DIVSELb	**Q_2, Q_3 Outputs**
L	Divide by 4
H	Divide by 6

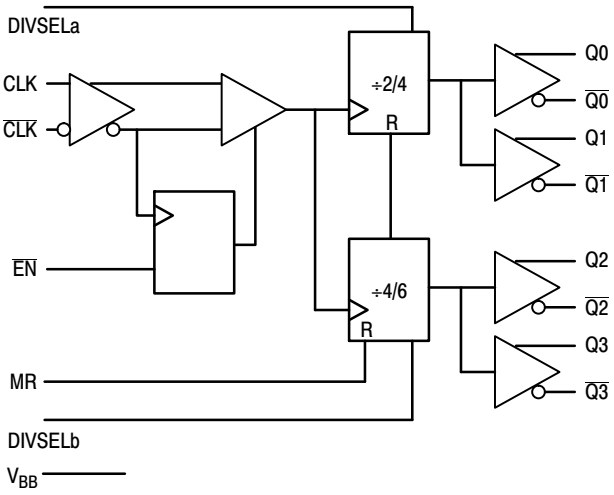


Figure 2. Logic Diagram

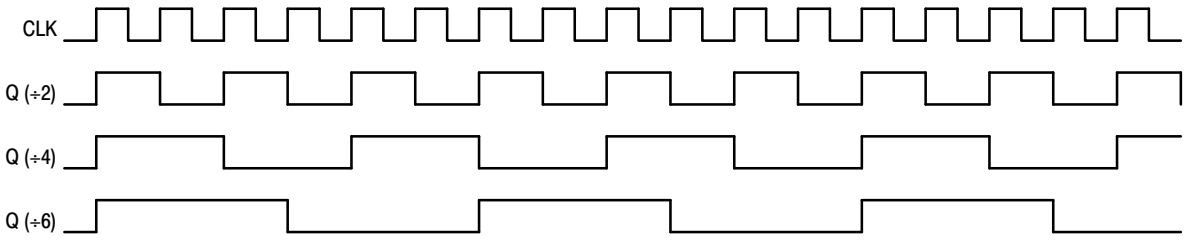


Figure 3. Timing Diagrams

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 to 0 −6 to 0	V
I_{out}	Output Current	Continuous Surge		50 100	mA
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC−20 WB	90 60	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC−20 WB	30 to 35	°C/W
T_{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. LVPECL DC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V (Note 1))

		−40°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		50	59		50	59		54	61	mA
V_{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6) V_{PP} < 500 mV V_{PP} ≥ 500 mV	 1.3 1.5		 2.9 2.9	 1.2 1.4		 2.9 2.9	 1.2 1.4		 2.9 2.9	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1.0 V.

Table 5. LVNECL DC CHARACTERISTICS (V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 4))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		50	59		50	59		54	61	mA
V_{OH}	Output HIGH Voltage (Note 5)	−1085	−1005	−880	−1025	−955	−880	−1025	−955	−880	mV
V_{OL}	Output LOW Voltage (Note 5)	−1830	−1695	−1555	−1810	−1705	−1620	−1810	−1705	−1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	−1810		−1475	−1810		−1475	−1810		−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6) V_{PP} < 500 mV V_{PP} ≥ 500 mV	 −2.0 −1.8		 −0.4 −0.4	 −2.1 −1.9		 −0.4 −0.4	 −2.1 −1.9		 −0.4 −0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

4. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
5. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
6. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1.0 V.

Table 6. AC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V or V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 7))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
fmax	Maximum Toggle Frequency	1000			1000			1000			MHz
t_{PLH} t_{PHL}	Propagation Delayed Output CLK to Q (Diff) CLK to Q (S.E.) MR to Q	 850 850 600		 1150 1150 900	 900 900 610		 1200 1200 910	 950 950 630		 1250 1250 930	ps
t_{SKEW}	Within-Device Skew (Note 8) $Q_0 - Q_3$ Part-to-Part $Q_0 - Q_3$ (Diff)			 50 200			 50 200			 50 200	ps
tJITTER	Random CLOCK Jitter (RMS) @ 1000 MHz		2.0	3.0		2.0	3.0		2.0	3.0	ps
t_S	Setup Time $\overline{EN}$ to $\overline{CLK}$ DIVSEL to CLK	 250 400			 250 400			 250 400			ps
t_H	Hold Time $\overline{CLK}$ to $\overline{EN}$ CLK to Div_Sel	 100 150			 100 150			 100 150			ps
V_{PP}	Input Swing (Note 9) CLK	250		1000	250		1000	250		1000	mV
t_{RR}	Reset Recovery Time			100			100			100	ps
t_{PW}	Minimum Pulse Width CLK MR	 500 700			 500 700			 500 700			ps
t_r, t_f	Output Rise/Fall Times Q (20% − 80%)	280		550	280		550	280		550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

7. V_{EE} can vary ±0.3 V. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
8. Skew is measured between outputs under identical transitions.
9. V_{PP}(min) is minimum input swing for which AC parameters are guaranteed. The device will function reliably with differential inputs down to 100 mV.

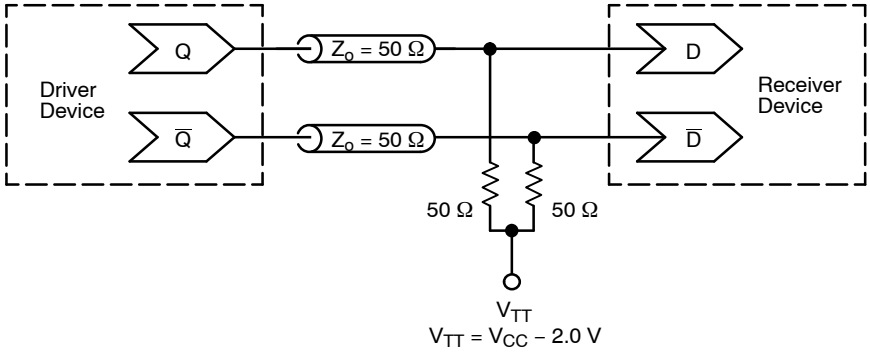
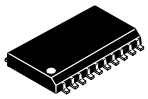


Figure 4. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1405/D	–	ECL Clock Distribution Techniques
AN1406/D	–	Designing with PECL (ECL at +5.0 V)
AN1503/D	–	ECLinPS™ I/O SPiCE Modeling Kit
AN1504/D	–	Metastability and the ECLinPS Family
AN1568/D	–	Interfacing Between LVDS and ECL
AN1672/D	–	The ECL Translator Guide
AND8001/D	–	Odd Number Counters Design
AND8002/D	–	Marking and Date Codes
AND8020/D	–	Termination of ECL Logic Devices
AND8066/D	–	Interfacing with ECLinPS
AND8090/D	–	AC Characteristics of ECL Devices

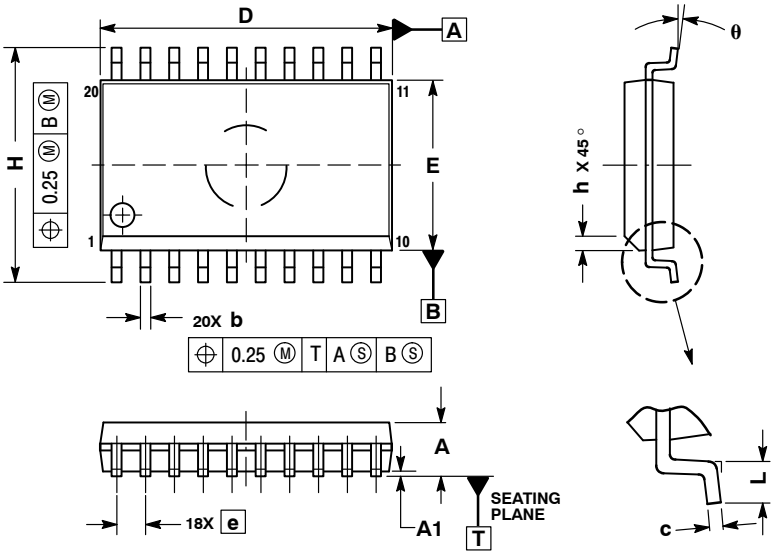
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

SOIC–20 WB
CASE 751D–05
ISSUE H

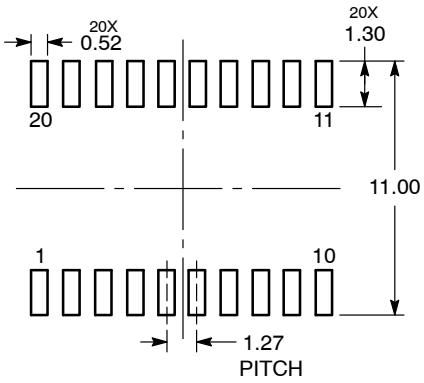
DATE 22 APR 2015



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

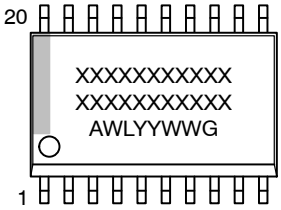
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98ASB42343B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**SOIC–20 WB**		**PAGE 1 OF 1**

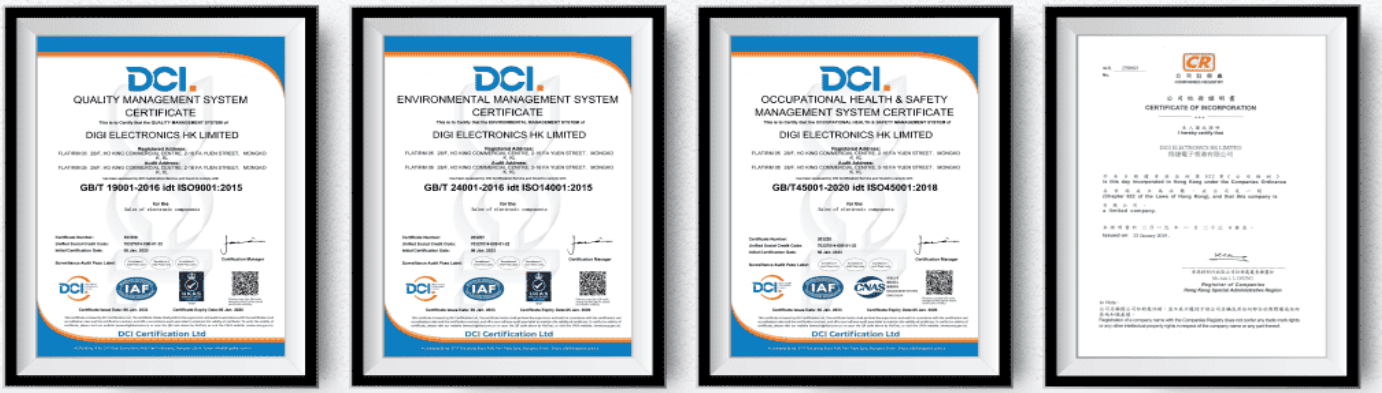
ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.